

Does JCET Group offer optical module packaging and testing services



Overview

The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider - including IC design and characterization, wafer bumping, packaging, test, and shipment to end customers. Shanghai, China, January 21, 2026 — JCET Group today announced a key milestone in co-packaged optics (CPO). The company has delivered customer samples of its silicon photonics engine developed on the XDFOI ® advanced packaging platform. JCET Group primarily serves sectors such as mobile, communication, compute, consumer, automotive, and industrial.) was founded in November 1998 and listed on the main board of the Shanghai Stock Exchange in 2003. 275 Binjiang Middle Road, Jiangyin City, Jiangsu Province, it is a globally leading. A leading global provider of semiconductor system integration packaging and testing services, specializing in the manufacturing of semiconductor devices and similar components. Ranked as the third-largest Outsourced Semiconductor Assembly and Test (OSAT) company worldwide.

Article Content

JCET Delivers Silicon Photonics Engine Samples, Marks CPO Milestone

JCET will continue to increase investment in advanced packaging, with a focus on multidimensional heterogeneous integration and optical test capabilities, to support high-performance ...

JCET Group — Packaging Solutions

JCET offers a full spectrum of semiconductor packaging services to meet diverse customer needs, spanning lead-frame packaging, substrate-based packaging, flip-chip interconnects, and advanced ...

JCET Group | Semiconductor Materials and Equipment

Our comprehensive portfolio covers a wide spectrum of semiconductor applications such as mobile, communication, compute, consumer, automotive and industry etc., through advanced wafer level ...

JCET Group — Test Solutions

Our full turnkey test services, which include wafer bump, probe, final test, post-test, and system level test, deliver the lowest cost of test for our customers with the highest possible throughput and faster ...

JCET Group Co., Ltd. integrated circuit manufacturing and technical ...

JCET Group Co., Ltd. is a global leader in semiconductor micro-system integration and packaging and testing services.

JCET Advanced Packaging

The company offers packaging and test services, including wafer bumping, probing, grinding, and various IC packaging solutions, as well as RF, analog, digital, and mixed signal testing.

JCET, The Republic of Korea

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JCET's Co-Packaged Optics: Enabling Next-Gen ...

By integrating optical engines with ASICs in a single package, we achieve shorter optical paths, optimized thermal management, and reliable system-level ...

JCET's Co-Packaged Optics: Enabling Next-Gen Performance | JCET Group ...

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JCET Group — Home

The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider—from IC design through test program development, wafer bump, wafer probe, multi ...

JCET Group

JCET delivers world-class services to its customers. The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider - including IC design and ...

Contact Us

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